



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/500,873 Confirmation No. : 1173  
First Named Inventor : Masahide HAYASHI  
Filed : July 7, 2004  
TC/A.U. : 2855  
Examiner : Andre J. Allen  
Docket No. : 056205.55095US  
Customer No. : 23911  
  
Title : Pressure Sensor, Flowmeter Electronic Component, and Method for Manufacturing the Same

REPLY

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This Reply is filed in response to the Office Action dated April 5, 2006.

Each of independent claims 15 and 18 is rejected under 35 U.S.C. 102, along with claims 17 and 20, as anticipated by Japanese Patent Publication 2001-116639 to Saito et al. Reconsideration is requested.

The Saito et al. publication discloses integrally molding a resin material casing 3 with a lead terminal formed by a metallic terminal or lead member 4, and placing a sensor chip 1 in the resin material casing 3. Seal resin 8, formed of a gel or adhesive with a relatively high hardness, is thereafter filled into a penetration region, at which the lead terminal 4 projects into the resin material casing 3. The Saito et al. publication also teaches that the seal resin 8 is potted and subjected to void-removing treatment, and then subjected to heat curing. It is therefore apparent that the seal resin 8 is a thermosetting resin.